

Understanding mechanisms of adhesion of SiO2 thin films evaporated on a polymeric substrate

Caroline Ho, Anita Dehoux, Joël Alexis, Loïc Lacroix, Olivier Dalverny, Sébastien Châtel, Bruce Faure

▶ To cite this version:

Caroline Ho, Anita Dehoux, Joël Alexis, Loïc Lacroix, Olivier Dalverny, et al.. Understanding mechanisms of adhesion of SiO2 thin films evaporated on a polymeric substrate. 43th International Conference on Metallurgical Coatings and Thin Films (ICMCTF), Apr 2016, San Diego, United States. Proceedings of the 43th International Conference on Metallurgical Coatings and Thin Films (ICM-CTF), pp.0, 2016. hal-02387348

HAL Id: hal-02387348 https://hal.science/hal-02387348

Submitted on 3 Dec 2019 $\,$

HAL is a multi-disciplinary open access archive for the deposit and dissemination of scientific research documents, whether they are published or not. The documents may come from teaching and research institutions in France or abroad, or from public or private research centers. L'archive ouverte pluridisciplinaire **HAL**, est destinée au dépôt et à la diffusion de documents scientifiques de niveau recherche, publiés ou non, émanant des établissements d'enseignement et de recherche français ou étrangers, des laboratoires publics ou privés.



Open Archive Toulouse Archive Ouverte

OATAO is an open access repository that collects the work of Toulouse researchers and makes it freely available over the web where possible

This is an author's version published in: http://oatao.univ-toulouse.fr/23316

To cite this version:

Ho, Caroline and Dehoux, Anita and Alexis, Joël and Lacroix, Loïc and Dalverny, Olivier and Châtel, Sébastien and Faure, Bruce Understanding mechanisms of adhesion of SiO2 thin films evaporated on a polymeric substrate. (2016) In: 43th International Conference on Metallurgical Coatings and Thin Films (ICMCTF), 25 April 2016 - 29 April 2016 (San Diego, United States). (Unpublished)

Any correspondence concerning this service should be sent to the repository administrator: <u>tech-oatao@listes-diff.inp-toulouse.fr</u>

Understanding Mechanisms of Adhesion of SiO₂ Thin Film Deposited on a Polymeric Substrate

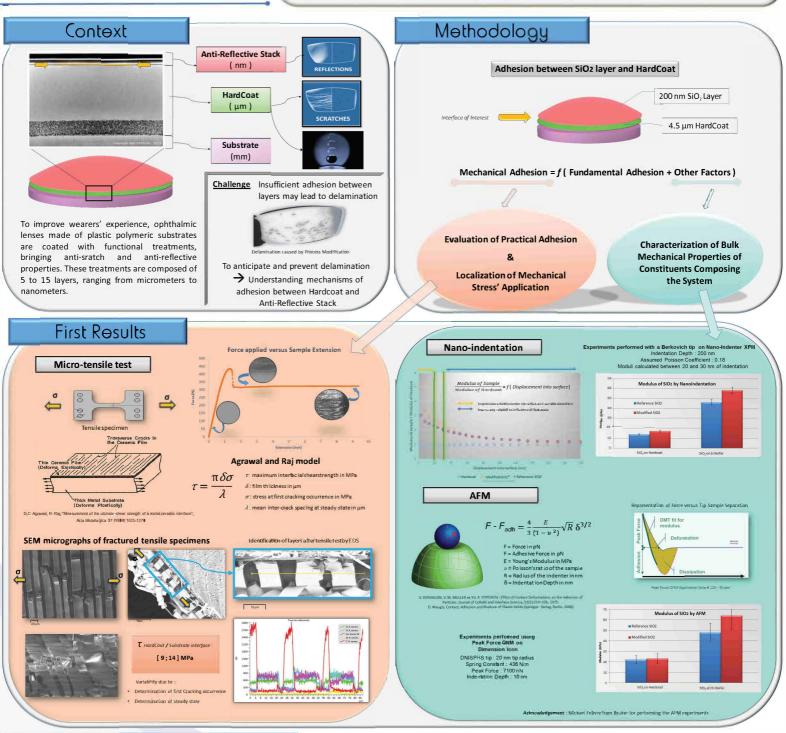
C. Ho^{1,2}, A. Dehoux², J. Alexis¹, L. Lacroix¹, O. Dalverny¹, S. Châtel², B. Faure²



 Laboratoire Génie de Production ENIT-INP, University of Toulouse, Tarbes, France
Thin Films Group, R&D Physico-Chemistry, Essilor International,

Créteil, France

Contact : caroline ho@enit.fr Abstract : A better understanding of mechanisms of adhesion between a 200 nm thick silicon dioxide layer and a 4.5 µm thick polymeric hardcoat is indispensable for an efficient adhesion at the interface. To reach this purpose, focus is placed on two axes: finding an applicable and effective method to quantify adhesion and in parallel, characterizing mechanical properties of materials composing the system. The second axis is needed to obtain data to feed modeling codes, enabling a better analysis of the adhesion experiment. Modulus of modified SiO₂ was found to be roughly 20% higher than reference SiO₂, by nanoindentation. AFM experiments showed no difference between modified and reference SiO₂. Currently, an investigation to detect cracks at the interface of interest for micro-tensile test is ongoing. Adhesion tests, such as micro-compression will be performed as well.



Conclusion and prospects

First micro-tensile experiments suggest that most noticeable cracks are located at the hardcoat/substrate interface. This was determined by EDS on fractured areas, after tensile stress. Modulus of modified SiO₂ was found to be roughly 20% higher than reference SiO₂ by nanoindentation. Considering the high standard deviation of moduli measured by AFM, no significant difference between moduli of modified and reference SiO₂ was observed by AFM. However, an important difference between moduli of SiO₂ on lens and on Si wafer was observed. This exposes unexpected influence of substrate on mechanical measurements using AFM, which has been hypothetically attributed to impact of Peak Force high frequency oscillations on viscoelastic substrates. Currently, an investigation to detect cracks at the interface of interest after micro-tensile test is ongoing. Other adhesion tests, such as micro-compression will be performed as well.



